



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D

*\* : Required Field*

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2015-09-10
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Authorized Representative *</b>	Rossana Bonaccorso	<b>Representative Title</b>	IPD MD CHAMPION
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**

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**Legal Statement**

<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard
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**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	ACWB*EAY25V4	A	ZS1A	2015-09-10
Amount	UoM	Unit type	ST ECOPACK Grade	
14.00	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SOT	2.9,1.625,1.175	6	flat	
Comment	Package: SOT 23 - 6L, MD valid for CP:ESDA25SC6Y.			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-15th June 2015				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	ACWB*EAY25V4					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or Dies (choose)	Other inorganic materials	0.628	mg	supplier	die	Silicon (Si)	7440-21-3		0.595	mg	947368	42429
				supplier	metallization	Aluminium (Al)	7429-90-5		0.006	mg	9569	429
				supplier	Passivation	Silicon Nitride	12033-89-5		0.002	mg	3190	143
				supplier	Passivation	Silicon Oxide	7631-86-9		0.010	mg	15949	714
				supplier	back side metallization	Chromium (Cr)	7440-47-3		0.001	mg	1595	71
				supplier	back side metallization	Gold (Au)	7440-57-5		0.001	mg	1595	71
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.005	mg	7974	357
				supplier	polymer die coating	PIX1 Gamma-butyrolactone	96-48-0		0.008	mg	12759	571
				supplier	alloy	Copper(CU)	7440-50-8		5.880	mg	950687	420000
				supplier	alloy	Iron(Fe)	7439-89-6		0.142	mg	22959	10143
Leadframe	Copper and its alloy	6.185	mg	supplier	alloy	Iron Phosphide(FeP)	26508-33-8		0.005	mg	808	357
				supplier	alloy	Zinc(Zn)	7440-66-6		0.008	mg	1293	571
				supplier	metallization	Silver(Ag)	7440-22-4		0.150	mg	24252	10714
				supplier	glue	Silver(Ag)	7440-22-4		0.074	mg	732673	5286
				supplier	glue	Acrylate monomer	Proprietary		0.015	mg	148515	1071
				supplier	glue	Acrylate oligomer	Proprietary		0.008	mg	79208	571
Die attach	Other organic material	0.101	mg	supplier	glue	Bismaleimide resin	35325-39-4		0.003	mg	29703	214
				supplier	glue	Epoxy resin	25068-38-6		0.001	mg	9901	71
				supplier	wire	Gold (Au)	7440-57-5		0.159	mg	1000000	11357
				supplier	glue	Silica Fused	60676-86-0		5.836	mg	867033	416857
Bonding wires	Other inorganic material	0.159	mg	supplier	wire	Gold (Au)	7440-57-5		0.159	mg	1000000	11357
				supplier	mold comp	Epoxy Resin	25068-38-6		0.538	mg	79929	38429
				supplier	mold comp	Phenol Resin	29690-82-2		0.336	mg	49918	24000
Encapsulation	Other Organic Materials	6.731	mg	supplier	mold comp	Carbon Black	1333-86-4		0.021	mg	3120	1500
				supplier	mold comp	Tin (Sn)	7440-31-5		0.196	mg	1000000	14000
Connections coating	Solder	0.196	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		0.196	mg	1000000	14000